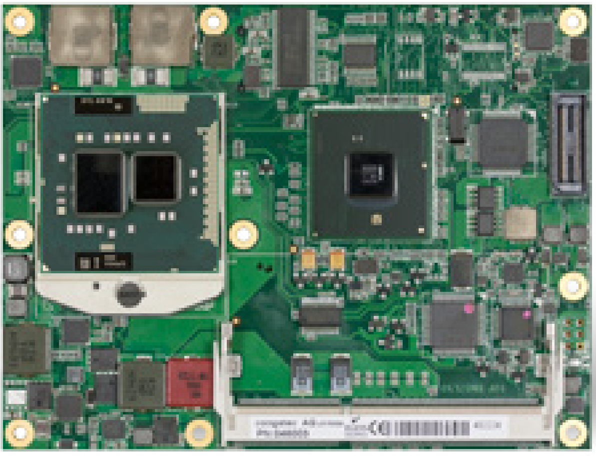
conga-BM57

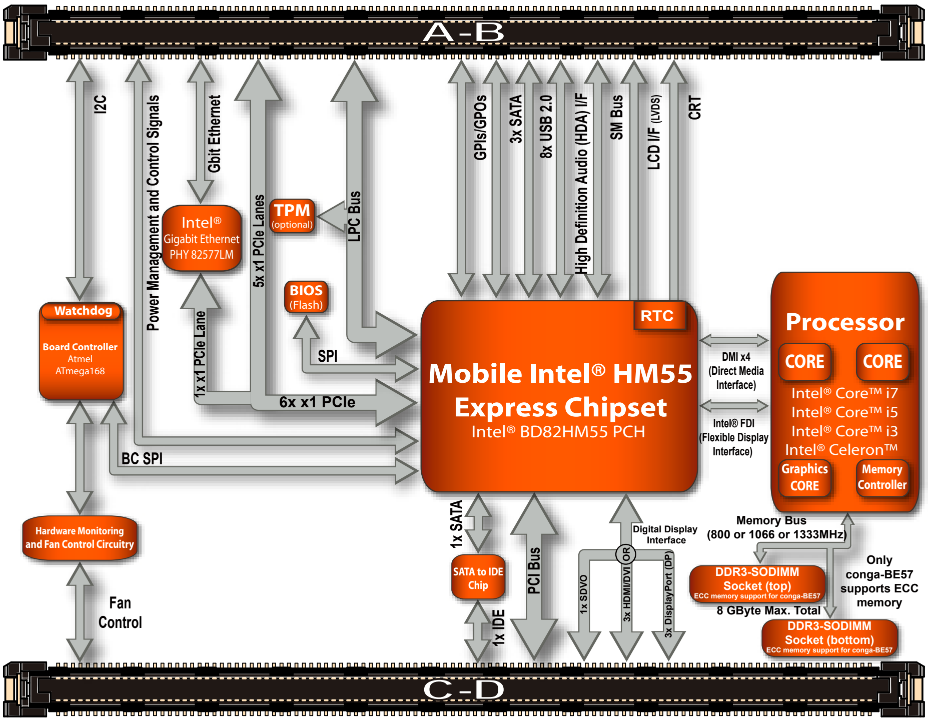
Maximum Computing Performance



- up to Intel® Core™ i7 Processors 2.66 GHz
- Highest end graphics performance
- Intel® Turbo Boost Technology up to 3.33 GHz

Formfactor	COM Express™ Basic | (95 x 125 mm) | Type II Connector Layout
CPU	Intel® Core™ i7-620M 2.66 GHz 32 nm process 4MB cache 1066 MHz TDP 35 W PGA package Intel® Core™ i5-520M 2.4 GHz 32 nm process 3MB cache 1066 MHz TDP 35 W PGA package Intel® Celeron™ P4500 1.86 GHz 32 nm process 2MB cache TDP 35 W PGA package Integrated dual channel memory controller | up to 17.1 GByte/sec. memory bandwidth Integrated Intel® HD Graphics with dynamic frequency up to 667 MHz Intel® Clear Video HD Technology
DRAM	2 Sockets | SO-DIMM DDR3 1333 MHz | up to 8 GByte
Chipset	Intel® 5 Series Chipset: Intel® HM55
Ethernet	Intel® 82577LM Ethernet PHY
I/O Interfaces	5x PCI Express™ lanes | 3x Serial ATA® (AHCI) no RAID support | 1x EIDE (UDMA-66/100) optional | 2x ExpressCard® | 8x USB 2.0 (EHCI) PCI bus 33 MHz Rev. 2.3 | LPC bus | I^2C bus (fast mode | 400 kHz | multi-master)
Sound	Digital High Definition Audio Interface with support for multiple audio codecs
Graphics	Processor integrated Mobile Intel® 5 Series HD graphics OpenGL 2.1 and DirectX10 support | Two independent pipelines for full dual view support | High performance hardware MPEG-2 decoding WMV9 (VC-1) and H.264 (AVC) support Blu-ray support @ 40 MBit/s | hardware motion compensation | no PEG support
LVDS	Dual channel LVDS transmitter | Supports flat panels 2x24 Bit interface | VESA mappings | resolutions up to 1920x1200 | Automatic Panel Detection via EDID/EPI
DisplayPort	3x DisplayPorts 1.1 shared with HDMI
HDMI	3x ports shared with DisplayPorts
CRT Interface	350 MHz RAMDAC | resolutions up to QXGA (2048x1536)
AUX Output	Supports one SDVO port shared with HDMI and DisplayPort capable of driving a 200MP pixel rate
congatec Board Controller	Multi Stage Watchdog | non-volatile User Data Storage | Manufacturing and Board Information | Board Statistics | BIOS Setup Data Backup I^2C bus (fast mode | 400 kHz | multi-master) | Power Loss Control
Embedded BIOS Features	AMI Aptio® UEFI 2.x firmware | 4 MByte serial SPI firmware flash
Security	The conga-BM57 can be optionally equipped with a discrete "Trusted Platform Module" (TPM). It is capable of calculating efficient hash and RSA algorithms with key lengths up to 2,048 bits and includes a real random number generator. Security sensitive applications such as gaming and e-commerce will benefit also with improved authentication | integrity and confidence levels.
Power Management	ACPI 3.0 with battery support
Operating Systems	Microsoft® Windows 8 | Microsoft® Windows 7 | Microsoft® Windows XP | Microsoft® Windows® embedded Standard | Linux
Power Consumption	Typ. application: tbd. | see manual for full details | CMOS Battery Backup
Temperature	Operating: 0 .. +60°C | Storage: -20 .. +80°C
Humidity	Operating: 10 - 90% r. H. non cond. | Storage: 5 - 95% r. H. non cond.
Size	95 x 125 mm (3.74" x 4.92")

conga-BM57 | Block diagram



conga-BM57 | Order Information

Article	PN	Description
conga-BM57/i5-520M	046001	Intel® Core™ i5-520M processor with 2.4GHz | 3MB L2 cache and 1066MT/s dual channel DDR3 memory interface
conga-BM57/i7-620M	046002	Intel® Core™ i7-620M processor with 2.66GHz | 4MB L2 cache and 1066MT/s dual channel DDR3 memory interface
conga-BM57/P4500	046005	Intel® Celeron® P4500 processor with 1.86 GHz | 2MB L2 cache and 800MT/s dual channel DDR3 SODIMM memory interface for up to 8GB
conga-BM57/CSP-HP-B	046022	Standard passive cooling solution for high performance COM Express module conga-BM57 with integrated heat pipes | 15mm silver fins and 20mm overall heat sink height. All standoffs are with 2.7mm bore hole
conga-BM57/CSP-HP-T	046023	Standard passive cooling solution for high performance COM Express module conga-BM57 with integrated heat pipes | 15mm silver fins and 20mm overall heat sink height. All standoffs are M2.5mm thread
conga-BM57/CSA-HP-B	046024	Standard active cooling solution for high performance COM Express module conga-BM57 with integrated heat pipes | 15mm silver fins | 20mm overall heat sink height and integrated 12V fan. All standoffs are with 2.7mm bore hole
conga-BM57/CSA-HP-T	046025	Standard active cooling solution for high performance COM Express module conga-BM57 with integrated heat pipes | 15mm silver fins | 20mm overall heat sink height and integrated 12V fan. All standoffs are M2.5mm thread
conga-BM57/HSP-HP-B	046020	Standard heatspreader for high performance COM Express module conga-BM57 with integrated heat pipes. All standoffs are with 2.7mm bore hole
conga-BM57/HSP-HP-T	046021	Standard heatspreader for high performance COM Express module conga-BM57 with integrated heat pipes. All standoffs are M2.5mm thread
DDR3-SODIMM-1066 (1GB)	068750	DDR3 SODIMM memory module with 1066MT/s and 1GB RAM
DDR3-SODIMM-1066 (2GB)	068760	DDR3 SODIMM memory module with 1066MT/s and 2GB RAM
DDR3-SODIMM-1066 (4GB)	068765	DDR3 SODIMM memory module with 1066MT/s and 4GB RAM

Accessories		
conga-CEVAL	065749	Evaluation Carrier Board for COM Express Type 2 modules
conga-Cdebug	047854	COM-Express debugging platform. Including cable for COM | PS/2 and VGA.
conga-LDVI/EPI	011115	LVDS to DVI converter board for digital flat panels with onboard EEPROM
conga-HDMI/Display Port adapter	500014	The conga-HDMI/DisplayPort adapter is used fo convert the chipset graphic ports Port-B | Port-C and Port-D to the HDMI or DisplayPort Interface
conga-FPA2	047250	Flatpanel prototype adapter to develop your own flatpanel adapter Including cables set.
COM-Express-carrier-board-Socket-5	400007	Connector for COM-Express carrier boards | height 5mm | packing unit 4 pieces
COM-Express-carrier-board-Socket-8	400004	Connector for COM-Express carrier boards | height 8mm | packing unit 4 pieces

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- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.

Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)
Факс: 8 (812) 320-02-42
Электронная почта: org@eplast1.ru
Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.